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- Inputs Are TTL-Voltage Compatible
- Internal Look-Ahead for Fast Counting
- Carry Output for n-Bit Cascading
- Synchronous Counting
- Synchronously Programmable
- Package Options Include Plastic Small-Outline (M), Standard Plastic (E) and Ceramic (F) DIPs

description

The CD54ACT163 and CD74ACT163 devices are 4-bit binary counters. These synchronous, presettable counters feature an internal carry look-ahead for application in high-speed counting

12 Q_C

11 DQD

10 ENT

9 LOAD

C [] 5

D [] 6

ENP [] 7

GND ∏8

designs. Synchronous operation is provided by having all flip-flops clocked simultaneously so that the outputs change coincident with each other when instructed by the count-enable (ENP, ENT) inputs and internal gating. This mode of operation eliminates the output counting spikes normally associated with synchronous (ripple-clock) counters. A buffered clock (CLK) input triggers the four flip-flops on the rising (positive-going) edge of the clock waveform.

The counters are fully programmable; that is, they can be preset to any number between 0 and 9 or 15. Presetting is synchronous; therefore, setting up a low level at the load input disables the counter and causes the outputs to agree with the setup data after the next clock pulse, regardless of the levels of the enable inputs.

The clear function is synchronous. A low level at the clear ($\overline{\text{CLR}}$) input sets all four of the flip-flop outputs low after the next low-to-high transition of CLK, regardless of the levels of the enable inputs. This synchronous clear allows the count length to be modified easily by decoding the Q outputs for the maximum count desired. The active-low output of the gate used for decoding is connected to $\overline{\text{CLR}}$ to synchronously clear the counter to 0000 (LLLL).

The carry look-ahead circuitry provides for cascading counters for n-bit synchronous applications without additional gating. ENP, ENT, and a ripple-carry output (RCO) are instrumental in accomplishing this function. Both ENP and ENT must be high to count, and ENT is fed forward to enable RCO. Enabling RCO produces a high-level pulse while the count is maximum (9 or 15 with Q_A high). This high-level overflow ripple-carry pulse can be used to enable successive cascaded stages. Transitions at ENP or ENT are allowed, regardless of the level of CLK.

These devices feature a fully independent clock circuit. Changes at control inputs (ENP, ENT, or $\overline{\text{LOAD}}$) that modify the operating mode have no effect on the contents of the counter until clocking occurs. The function of the counter (whether enabled, disabled, loading, or counting) is dictated solely by the conditions meeting the stable setup and hold times.

The CD54ACT163 is characterized for operation over the full military temperature range of –55°C to 125°C. The CD74ACT163 is characterized for operation from –40°C to 85°C.



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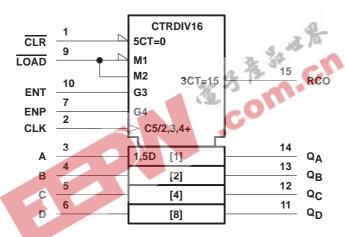
FUNCTION TABLE

		IN	IPUTS			OUTPUTS		FUNCTION
CLR	CLK	ENP	ENT	LOAD	A,B,C,D	Qn	RCO	FUNCTION
L	↑	Χ	Χ	Χ	Χ	L	L	Reset (clear)
h	↑	Χ	Χ	I	I	L	L	Parallel load
h	\uparrow	X	Χ	I	h	Н	Note 1	Farallel load
h	↑	h	h	h	Х	Count	Note 1	Count
h	Χ	- 1	Χ	h	Х	q _n	Note 1	Inhibit
h	Χ	Χ	1	h	Χ	q _n	L	ITITIIDIL

 $H = high\ level,\ L = low\ level,\ X = don't\ care,\ h = high\ level\ one\ setup\ time\ prior\ to\ the\ CLK\ low-to-high\ transition,\ q = the\ state\ of\ the\ referenced\ output\ prior\ to\ the\ CLK\ low-to-high\ transition,\ \uparrow = CLK\ low-to-high\ transition$

NOTE 1: The RCO output is high when ENT is high and the counter is at terminal count (HHHH).

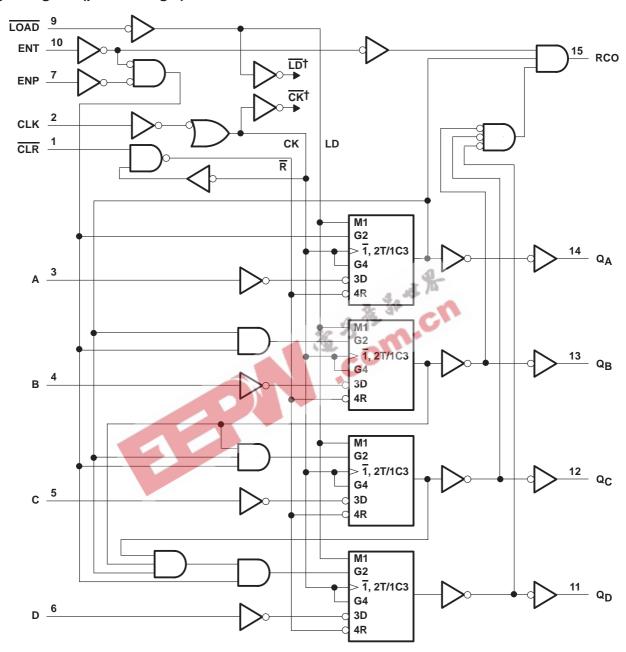
logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



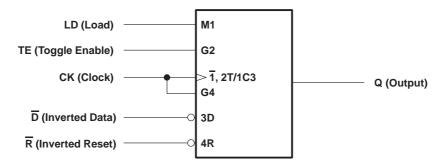
logic diagram (positive logic)



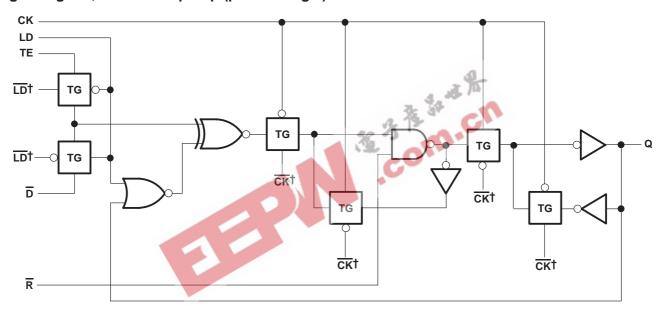
[†] For simplicity, routing of complementary signals $\overline{\text{LD}}$ and $\overline{\text{CK}}$ is not shown on this overall logic diagram. The uses of these signals are shown on the logic diagram of the D/T flip-flops.

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logic symbol, each D/T flip-flop



logic diagram, each D/T flip-flop (positive logic)



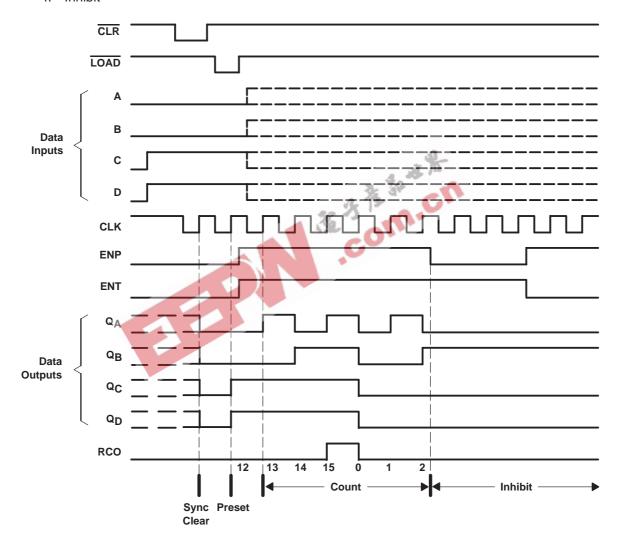
 † The origins of $\overline{\text{LD}}$ and $\overline{\text{CK}}$ are shown in the logic diagram of the overall device.

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typical clear, preset, count, and inhibit sequence

The following sequence is illustrated below:

- 1. Clear outputs to zero (synchronous)
- 2. Preset to binary 12
- 3. Count to 13, 14, 15, 0, 1, and 2
- 4. Inhibit



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absolute maximum ratings over operating free-air temperature range[†]

Supply voltage range, V _{CC}	0.5 V to 6 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 2)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) (see Note 2)	±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±50 mA
Continuous current through V _{CC} or GND	±100 mA
Package thermal impedance, θ _{JA} (see Note 3): E package	67°C/W
M package	
Storage temperature range, T _{sto}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 4)

			T _A = 25°C CD54		D54ACT163		CD74ACT163	
		MIN	MAX	MHN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage	4.5	5.5	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2	4	2		2		V
VIL	Low-level input voltage	2	0.8		0.8		0.8	V
٧ _I	Input voltage	0	VCC	0	VCC	0	VCC	V
VO	Output voltage	0	Vcc	0	VCC	0	VCC	V
loh	High-level output current		-24		-24		-24	mA
loL	Low-level output current		24		24		24	mA
Δt/Δν	Input transition rise or fall rate	0	10	0	10	0	10	ns
TA	Operating free-air temperature			- 55	125	- 40	85	°C

NOTE 4: All unused inputs of the device must be held at VCC or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



NOTES: 2. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

^{3.} The package thermal impedance is calculated in accordance with JESD 51.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		Vaa	$T_A = 2$	25°C	CD54ACT163		CD74ACT163		UNIT
PARAMETER	TEST COND	VCC	MIN	MAX	MIN	MAX	MIN	MAX	UNIT	
<i>\\</i>		I _{OH} = -50 μA	4.5 V	4.4		4.4		4.4		V
	\\. = \\. or \\.	$I_{OH} = -24 \text{ mA}$	4.5 V	3.94		3.7		3.8		
VOH	VI = VIH or VIL	$I_{OH} = -50 \text{ mA}^{\dagger}$	5.5 V	_		3.85		_		
		$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V	_		_		3.85		
	VI = VIH or VIL	I _{OL} = 50 μA	4.5 V		0.1		0.1		0.1	· v
Vo.		I _{OL} = 24 mA	4.5 V		0.36		0.5		0.44	
VOL		$I_{OL} = 50 \text{ mA}^{\dagger}$	5.5 V		-		1.65		_	
		$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V		-		-		1.65	
lį	$V_I = V_{CC}$ or GND		5.5 V		±0.1		±1		±1	μΑ
Icc	$V_I = V_{CC}$ or GND,	I _O = 0	5.5 V		8		160		80	μΑ
ΔICC	V _I = V _{CC} -2.1 V		4.5 V to 5.5 V		2.4		3		2.8	mA
Ci					10		10		10	pF

[†] Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum $50-\Omega$ transmission-line drive capability at 85° C and $75-\Omega$ transmission-line drive capability at 125° C.

ACT INPUT LOAD TABLE

INPUT	UNIT LOAD
A, B, C, or D	0.13
CLK	1
CLR, ENT	0.83
LOAD	0.67
ENP	0.5

Unit Load is Δl_{CC} limit specified in electrical characteristics table (e.g., 2.4 mA at 25°C).

timing requirements over recommended operating conditions (unless otherwise noted)

				CT163	T163 CD74ACT163		UNIT
			MIN	MAX	MIN	MAX	UNIT
fclock	Clock frequency			80		91	MHz
t _W	Pulse duration	CLK high or low	6.2		5.4		ns
	Setup time, before CLK↑	A, B, C, or D	5		4.4		ns
l .		ENP or ENT	6		5.3		
t _{su}		LOAD low	7.5		6.6		
		CLR inactive	7.5		6.6		
	Hold time, after CLK↑	A, B, C, or D	0		0		
th		ENP or ENT	0		0		ns
		LOAD low	0		0		
		CLR inactive	0		0		

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switching characteristics over recommended operating conditions, C_L = 50 pF (unless otherwise noted) (see Figure 1)

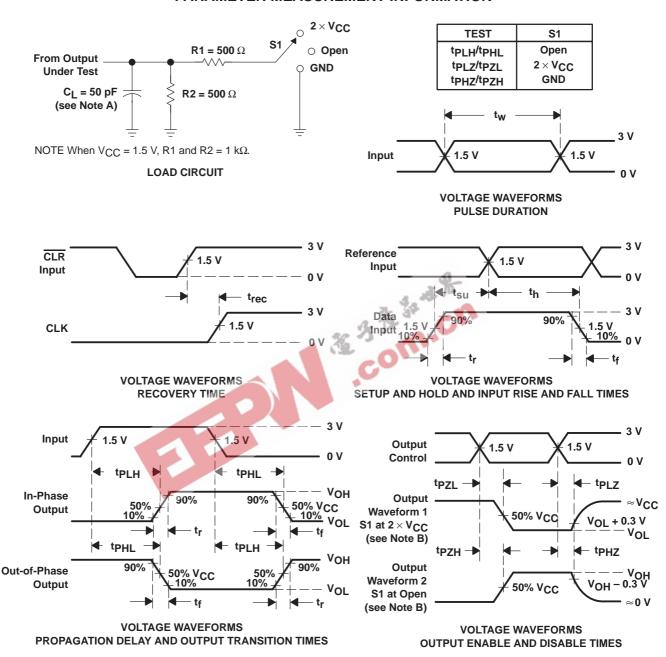
PARAMETER	FROM	то	CD74ACT163		CD74ACT163		UNIT
	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	UNIT
f _{max}			80		91		MHz
^t pd	CLK	RCO	4.2	16.7	4.3	15.2	
	CLK	Any Q	4.1	16.5	4.2	15	ns
	ENT	RCO	2.7	10.8	2.8	9.8	

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance	No load	66	pF



PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50~\Omega$, $t_f = 3~ns$, $t_f = 3~ns$. Phase relationships between waveforms are arbitrary.
- D. For clock inputs, f_{max} is measured with the input duty cycle at 50%.
- E. The outputs are measured one at a time with one input transition per measurement.
- F. tpLH and tpHL are the same as tpd.
- G. tpzL and tpzH are the same as ten.
- H. tpLz and tpHz are the same as tdis.

Figure 1. Load Circuit and Voltage Waveforms



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